

to have substantially same radius as that of a substrate or semiconductor wafer etched.

Horiuchi at col. 3, ll. 57-63 (sic).

There does not appear to be any teaching or suggestion of the use of a sealing ring having the claimed thermal conductivity properties. Indeed, it appears that Horiuchi et al. fail to appreciate the advantages provided by such a heat transferring seal and, therefore, cannot be said to anticipate or obviate the presently claimed assemblies.

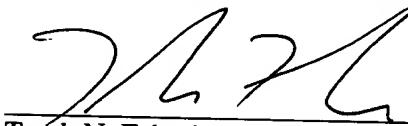
Likewise, Cathey, Jr., U.S. Patent No. 5,096,536, fails to teach or suggest such a heat transferring seal. Cathey, Jr. does disclose the use of O-ring seals between a wafer and an electrode, however, there does not appear to be any discussion or suggestion of the use of such seals having properties similar to the claimed heat transferring seal. Accordingly, the present claims are patentable over Cathey, Jr.

Please charge any deficiencies of fees associated with this communication to our Deposit Account No. 02-2666.

Respectfully submitted,

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